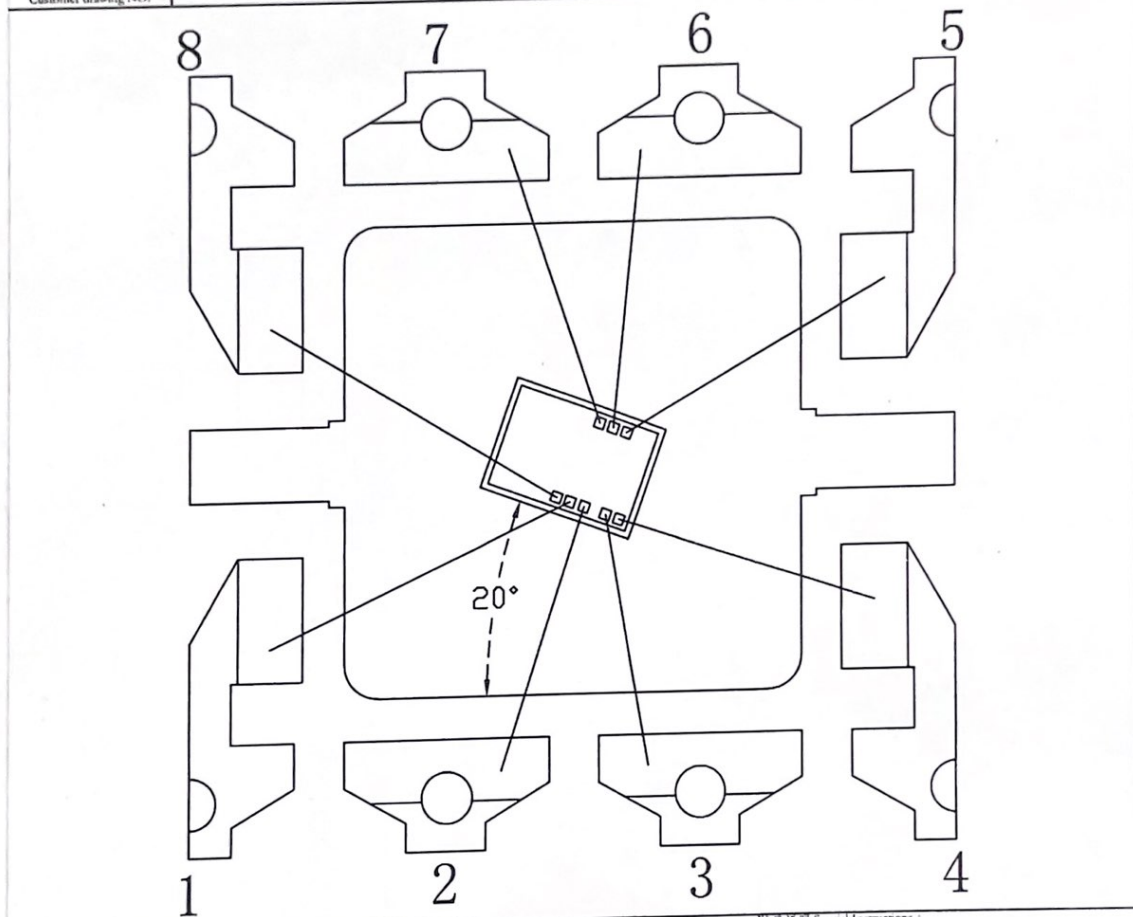


<b>池州华宇电子科技股份有限公司</b> CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO., LTD. <b>焊线图纸 Bonding Diagram</b>				客户代码 Customer No.	008	线号 Drawing No.	HY-PX-008-746 A	
产品名称 Product Type				HS5146_M1		封装类型 PKG Type	SOP8L (12R)	
焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线根数 NO. of wire	焊线总长(μm) Total wire length	最长线长(μm) Longest wire length	最短线长(μm) Shortest wire length	型材料型号(绿色环保) Compound Type (Green)		LF 载体尺寸 LF Pad Size
合金丝 Ag	20	8	13329	1652	1244	优选(Preferred): EME-G630AY 备选(Optional): CEL-1702HF		SOP8L-12R (90°/9mmil) (2286*2286μm <sup>2</sup> )
客户图号 Customer drawing NO.								



载带传送方向(照片): L/F Direction (D/A): <b>椭圆孔</b> 	实物图: Chip photo: 	特殊说明 Special Instructions: DB注意: 1. 芯片居中放置并顺时针旋转20°;
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注意: 基岛全镀银

说明 Description	贴片胶类型 Epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BPP(μm <sup>2</sup> )	最小焊盘间距 Min BPP(μm)	铜垫厚度(μm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	贴片通孔直径 Stress line (μm)	晶圆尺寸 Wafer Size	是否足 Is it full	减薄厚度 (μm) Wedge Thickness
A芯: DIE A	导电胶 (conductivity) S210	DB2	730*500(μm <sup>2</sup> ) 28.74*19.69(mil <sup>2</sup> )	50*50	70	2	是/Yes	60	8	否/NO	300
B芯: DIE B											
C芯: DIE C											
编制 Prepared by	2024.4.25		制图日期 Create Date	2024/4/25		生效日期 Effective Date					
研发审核 R&D Check	2024.4.25		产品工程审核 PE Check			批准 Approved by					
客户确认签字/盖章: Customer Signature										2024.04.26	

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